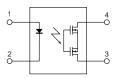


## RF (Radio Frequency) C X R 10 SSOP Type

# PhotoMOS RELAYS



mm inch



#### **FEATURES**

#### 1. Reduced package size

Lower surface has been reduced 60% and mounting space 40% compared to conventional 4-pin SOP type.

#### 2. Lower output capacitance and onresistance

Output capacitance(C): 1.0pF (typ.) ON resistance(R):  $9.5\Omega$  (typ.)

3. Mounting space has been reduced and output signals have been improved by using new flat lead terminals.





#### 4. High speed switching

Turn on time: 0.02ms Turn off time: 0.02ms

#### TYPICAL APPLICATIONS

#### Measuring and testing equipment

- 1. Test equipment IC tester, Liquid crystal driver tester, semiconductor performance tester
- 2. Board tester Bear board tester, In-circuit tester, function tester
- 3. Medical equipment Ultrasonic wave diagnostic machine
- 4. Multi-point recorder Warping, thermo couple

#### **TYPES**

Circuit	Туре	Output rating*		Tape and reel	Packing quantity	
arrangement		Load voltage	Load current	Picked from the 1/4-pin side	Picked from the 2/3-pin side	in tape and reel
1 Form A	AC/DC type	40 V	120 mA	AQY221N2VY	AQY221N2VW	3,500 pcs.

<sup>\*</sup> Indicate the peak AC and DC values.

Notes: (1) Tape package is the standard packing style.

(2)For space reasons, the initial letters of the product number "AQY and V", the package type indicator "Y" and "W" are omitted from the seal.

#### RATING

1. Absolute maximum ratings (Ambient temperature: 25°C 77°F)

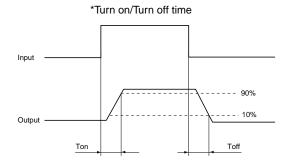
Item		Symbol	AQY221N2V	Remarks
	LED forward current	lF	50mA	
Input	LED reverse voltage	VR	3V	
	Peak forward current	IFP	1A	f=100 Hz, Duty factor=0.1%
	Power dissipation	Pin	75mW	
Output	Load voltage (peak AC)	VL	40V	
	Continuous load current (peak AC)	l <sub>L</sub>	0.12A	Peak AC,DC
	Peak load current	peak	0.3A	100 ms (1 shot), V <sub>L</sub> = DC
	Power dissipation	Pout	250mW	
Total power dissipation		Р⊤	300mW	
I/O isolation voltage		Viso	1,500V AC	
Temperature limits	Operating	Topr	-40°C to +85°C -40°F to +185°F	Non-condensing at low temperatures
	Storage	T <sub>stg</sub>	-40°C to +100°C -40°F to +212°F	

2. Electrical characteristics (Ambient temperature: 25°C 77°F)

Item				Symbol	AQY221N2V	Condition
	LED operate current		Typical	l <sub>Fon</sub> -	1.0 mA	IL = 80 mA
Input			Maximum		3.0 mA	IL = 80 MA
	LED turn off current		Minimum	<b>I</b> Foff	0.2 mA	IL = 80 mA
			Typical		0.9 mA	
	LED dropout voltage		Typical	VF	1.14 V (1.35 V at I <sub>F</sub> = 50mA)	I <sub>F</sub> = 5mA
			Maximum		1.5 V	
	On resistance		Typical	Ron	9.5Ω	$I_F = 5mA$ $I_L = 80 mA$ Within 1 s on time
			Maximum		12.5Ω	
Output	Output capacitance		Typical	Cout	1.0 pF	$\begin{array}{c} I_F = 0 \\ V_B = 0 \ V \\ f = 1 \ MHz \end{array}$
Output			Maximum		1.5 pF	
	Off state leakage current		Typical	Leak	0.01 nA	I <sub>F</sub> = 0
			Maximum		10 nA	V∟ = Max.
Transfer characteristics	Switching speed	Turn on time*	Typical	Ton	0.02 ms	$I_F = 5mA$ $V_L = 10V$ $R_L = 125\Omega$
			Maximum		0.5ms	
		Turn off time*	Typical	Toff	0.02ms	$I_F = 5mA$ $V_L = 10V$ $R_L = 125\Omega$
			Maximum		0.2 ms	
	I/O capacitance		Typical	Ciso	0.8 pF	f = 1MHz
			Maximum		1.5 pF	V <sub>B</sub> = 0
	Initial I/O isolation resistance		Minimum	Riso	1,000ΜΩ	500V DC

Note: Recommendable LED forward current I<sub>F</sub> = 5 mA.

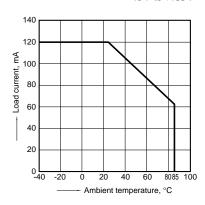
For type of connection, see Page 5.



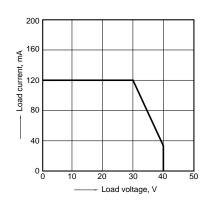
### **REFERENCE DATA**

1. Load current vs. ambient temperature characteristics

Allowable ambient temperature: -40°C to +85°C -40°F to +185°F

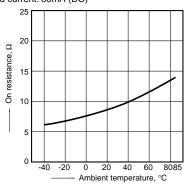


2. Load current vs. Load voltage characteristics Ambient temperature: 25°C 77°F



3. On resistance vs. ambient temperature characteristics

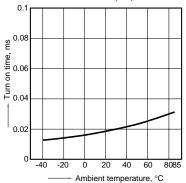
Measured portion: between terminals 3 and 4 LED current: 5 mA; Load voltage: Max. (DC); Load current: 80mA (DC)



#### AQY221N2V

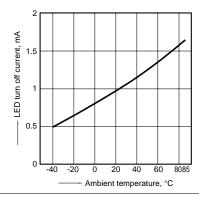
4. Turn on time vs. ambient temperature characteristics

Measured portion: between terminals 3 and 4 LED current: 5 mA; Load voltage: 10V (DC); Continuous load current: 80mA (DC)

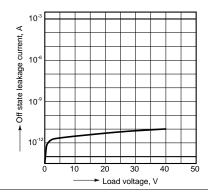


7. LED turn off current vs. ambient temperature characteristics

Load voltage: Max. (DC); Continuous load current: 80mA (DC)

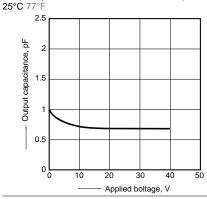


10. Off state leakage current Measured portion: between terminals 3 and 4 Ambient temperature: 25°C 77°F



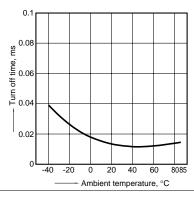
Applied voltage vs. output capacitance characteristics

Measured portion: between terminals 3 and 4 Frequency: 1 MHz, 30m Vrms; Ambient temperature: 25°C 77°F

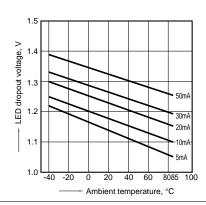


5. Turn off time vs. ambient temperature characteristics

LED current: 5 mA; Load voltage: 10V (DC); Continuous load current: 80mA (DC)

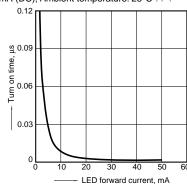


8. LED dropout voltage vs. ambient temperature characteristics LED current: 5 to 50 mA



11. LED forward current vs. turn on time characteristics

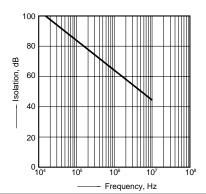
Measured portion: between terminals 3 and 4 Load voltage: 10V (DC); Continuous load current: 80mA (DC); Ambient temperature: 25°C 77°F



14. Isolation characteristics ( $50\Omega$  impedance)

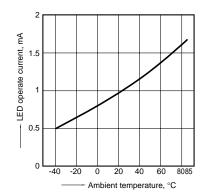
Measured portion: between terminals 3 and 4

Measured portion: between termina Ambient temperature: 25°C 77°F



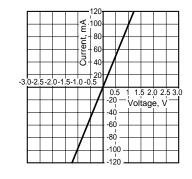
 LED operate current vs. ambient temperature characteristics Load voltage: Max. (DC);

Continuous load current: 80mA (DC)



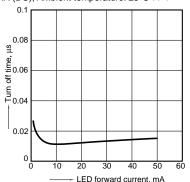
9. Voltage vs. current characteristics of output at MOS portion

Measured portion: between terminals 3 and 4 Ambient temperature: 25°C 77°F



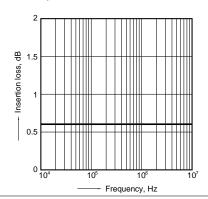
## 12. LED forward current vs. turn off time characteristics

Measured portion: between terminals 3 and 4 Load voltage: 10V (DC); Continuous load current: 80mA (DC); Ambient temperature: 25°C 77°F

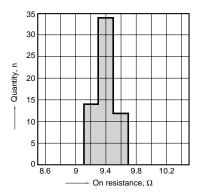


## 15. Insertion loss characteristics ( $50\Omega$ impedance)

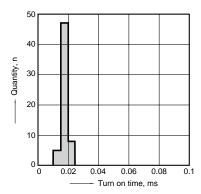
Measured portion: between terminals 3 and 4 Ambient temperature: 25°C 77°F



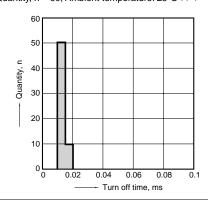
16. On resistance distribution Measured portion: between terminals 3 and 4 Continuous load current: 80mA (DC) Quantity, n=60; Ambient temperature: 25°C 77°F



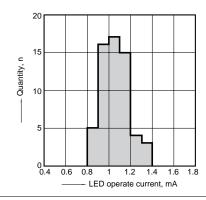
17. Turn on time distribution
Load voltage: 10V (DC)
Continuous load current: 80mA (DC)
Quantity, n = 60; Ambient temperature: 25°C 77°F



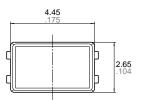
18. Turn off time distribution
Load voltage: 10V (DC)
Continuous load current: 80mA (DC)
Quantity, n = 60; Ambient temperature: 25°C 77°F

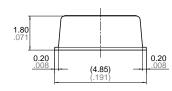


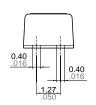
19. LED operate current distribution Load voltage: 10V (DC) Continuous load current: 80mA (DC) Quantity, n = 60; Ambient temperature: 25°C 77°F



#### **DIMENSIONS**

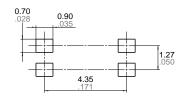






mm inch

Recommended mounting pad (TOP VIEW)



Tolerance:±0.1 ±.004

Terminal thickness = 0.15.006General tolerance:  $\pm 0.1 \pm .004$ 

#### SCHEMATIC AND WIRING DIAGRAMS

Notes: 1. E1: Power source at input side; VIN: Input voltage; IF: LED forward current; IIN: Input current; VL: Load voltage; IL: Load current

Notes. 1. E1. Fower source at input side, vin. Input voltage, if. EED forward current, in. Input current, v. Load voltage, ic. Load current							
Schematic	Output configuration	Load	Wiring diagram				
	1a	AC/DC	E1 T IF 2 IL VL (AC,DC)				

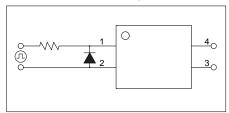
#### **CAUTIONS FOR USE**

#### 1. Short across terminals

Do not short circuit between terminals when relay is energized. There is possibility of breaking the internal IC.

#### 2. Surge voltages at the input

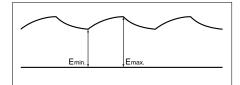
If reverse surge voltages are present at the input terminals, connect a diode in reverse parallel across the input terminals and keep the reverse voltages below the reverse breakdown voltage.



## 3. Recommended LED forward current (I<sub>F</sub>)

It is recommended that the LED forward current (I<sub>F</sub>) be kept at 5mA.

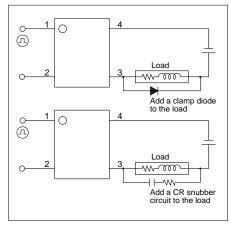
- **4. Ripple in the input power supply** If ripple is present in the input power supply, observe the following:
- 1) For LED operate current at  $E_{min}$ , maintain the value mentioned in the table of "3. Recommended LED forward current (IF)."
- 2) Keep the LED operate current at 50 mA or less at E<sub>max</sub>.



#### 5. Output spike voltages

1) If an inductive load generates spike voltages which exceed the absolute maximum rating, the spike voltage must be limited.

Typical circuits are shown below.



2) If spike voltages generated at the load are limited with a clamp diode and the circuit wires are long, spike voltages will occur by inductance.

Keep wires as short as possible to minimize inductance.

#### 6. Cleaning solvents compatibility

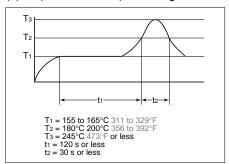
Dip cleaning with an organic solvent is recommended for removal of solder flux, dust, etc. Select a cleaning solvent from the following table. If ultrasonic cleaning is used, the severity of factors such as frequency, output power and cleaning solvent selected may cause loose wires and other defects. Make sure these conditions are correct before use. For details, please consult us.

actaile, picace corioait ac.				
Clear	ning solvent	Compatibility (O: Yes X: No)		
Chlorine base	Trichlene     Chloroethlene	Э		
Adueous	• Indusco • Hollis • Lonco Terg	0		
Alcohol base	IPA     Ethanol	Э		
Others	Thinner     Gasoline	×		

#### 7. Soldering

When soldering this terminals, the following conditions are recommended.

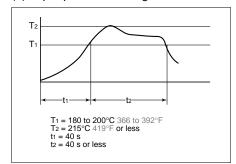
(1) IR (Infrared reflow) soldering method



(4) Soldering iron method Tip temperature: 280 to 300°C

536 to 572°F

Wattage: 30 to 60 W Soldering time: within 5 s (2) Vapor phase soldering method

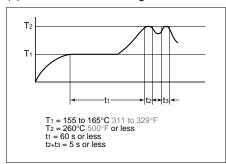


(5) Others

Check mounting conditions before using other soldering methods (hot-air, hot plate, pulse heater, etc.)

• The temperature profile indicates the temperature of the soldered terminal on the surface of the PC board. The ambient

(3) Double wave soldering method

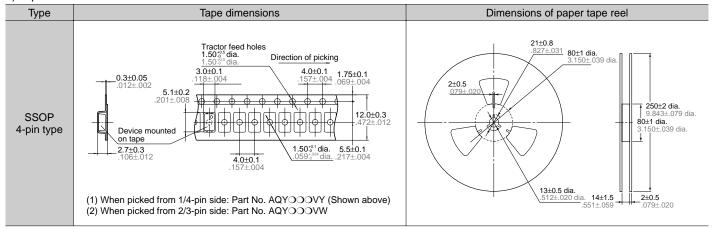


temperature may increase excessively. Check the temperature under mounting conditions.

 The conditions for the infrared reflow soldering apply when preheating using the VPS method.

#### 8. The following shows the packaging format

1) Tape and reel mm inch



#### 2) Storage

PhotoMOS relays implemented in SSOP types are sensitive to moisture and come in sealed moisture-proof packages. Observe the following cautions on storage.

- After the moisture-proof package is unsealed, take the devices out of storage as soon as possible (within 1 month at the most).
- If the devices are to be left in storage for a considerable period after the moistureproof package has been unsealed, it is recommended to keep them in another moisture-proof bag containing silica gel (within 3 months at the most).

#### 9. Transportation and storage

- Extreme vibration during transport will warp the lead or damage the relay.
   Handle the outer and inner boxes with care.
- 2) Storage under extreme conditions will cause soldering degradation, external appearance defects, and deterioration of the characteristics. The following storage conditions are recommended:
- Temperature: 0 to 45°C 32 to 113°F
- Humidity: Less than 70% R.H.
- Atomosphere: No harmful gasses such as sulfurous acid gas, minimal dust.

## 10. Applying stress that exceeds the absolute maximum rating

If the voltage or current value for any of the terminals exceeds the absolute maximum rating, internal elements will deteriorate because of the excessive voltage or current. In extreme cases, wiring may melt, or silicon P/N junctions may be destroyed.

As a result, the design should ensure that the absolute maximum ratings will never be exceeded, even momentarily. (Use at 15 V DC or lower and 9 V DC or lower is recommended.)

## 11. Deterioration and destruction caused by discharge of static electricity

This phenomenon is generally called static electricity destruction. This occurs when static electricity generated by various factors is discharged while the relay terminals are in contact. The result can producing internal destruction of the element.

To prevent problems from static electricity, the following precautions and measures should be taken when using your device.

- 1) Employees handling relays should wear anti-static clothing and should be grounded through protective resistance of 500 k $\Omega$  to 1 M $\Omega$ .
- 2) A conductive metal sheet should be placed over the work table. Measuring instruments and jigs should be grounded.
  3) When using soldering irons, either use irons with low leakage current, or ground the tip of the soldering iron. (Use of low-voltage soldering irons is also recommended.)
- 4) Devices and equipment used in assembly should also be grounded.5) When packing printed circuit boards and equipment, avoid using high-polymer materials such as foam styrene, plastic, and other materials which carry an

electrostatic charge.

6) When storing or transporting relays, the environment should not be conducive to generating static electricity (for instance, the humidity should be between 45 and 60%). Relays should always be protected using non-conductive packing materials.